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**Bib Data Sheet** 

**CONFIRMATION NO. 9360** 

FILING OR 371(c)							
10/17/2003 RULE	_	CLASS GROUP AR 356 2877		2877	T UNIT	ATTORNEY DOCKET NO. 501.33745CX4	
Shunji Maeda, Yokohama-shi, JAPAN; Yasuhiko Nakayama, Yokohama-shi, JAPAN; Minoru Yoshida, Yokohama-shi, JAPAN; Hitoshi Kubota, Fujisawa-shi, JAPAN; Kenji Oka, Fujisawa-shi, JAPAN;  *** CONTINUING DATA **********************************							
Foreign Priority claimed  35 USC 119 (a-d) conditions  met  Verified and  Acknowledged  Exampler's Signature  Initials		STATE OR COUNTRY JAPAN	SHEETS DRAWING 30		CLAII	MS -	INDEPENDENT CLAIMS
<b>ADDRESS</b> 020457							
TITLE  Manufacturing method of semiconductor substrate and method and apparatus for inspecting defects of patterns of an object to be inspected							
o to charge/credit DEPOSIT ACCOUNT			☐ All Fees ☐ 1.16 Fees ( Filing ) ☐ 1.17 Fees ( Processing Ext. of time ) ☐ 1.18 Fees ( Issue ) ☐ Other ☐ Credit				
	RULE  Ia, Yokohama-shi, JAPAN akayama, Yokohama-shi, JAPAN inida, Yokohama-shi, JAPAN inida, Yokohama-shi, JAPAN inida, Fujisawa-shi, JAPAN inijisawa-shi, JAPAN;  IATA ***********************************	RULE  Ia, Yokohama-shi, JAPAN; akayama, Yokohama-shi, JAPAN; aida, Yokohama-shi, JAPAN; ata, Fujisawa-shi, JAPAN; ata, Fujisawa-shi, JAPAN; ation is a CON of 10/098,478 03/18/2 PAT 6,404,498 ON of 09/107,432 06/30/1998 PAT ON of 08/539,886 10/06/1995 PAT AICATIONS  REIGN FILING LICENSE GRANTE  REIGN FILING LICENSE GRANTE  Allowance  Exampler's Signature  Initials  Thod of semiconductor substrate and aspected  EES: Authority has been given in Patentine Inspected	RULE  Ia, Yokohama-shi, JAPAN; akayama, Yokohama-shi, JAPAN; bida, Yokohama-shi, JAPAN; bida, Fujisawa-shi, JAPAN; bida, Fujisawa-shi, JAPAN; bidion is a CON of 10/098,478 03/18/2002 PAT 7,06 PAT 6,404,498 ON of 09/107,432 06/30/1998 PAT 6,263,099 ON of 08/539,886 10/06/1995 PAT 5,774,222  LICATIONS  REIGN FILING LICENSE GRANTED  REIGN FILING LICENSE GRANTED  STATE OR COUNTRY JAPAN  Hod of semiconductor substrate and method and anspected  EES: Authority has been given in Paper to charge/credit DEPOSIT ACCOU	RULE  Ida, Yokohama-shi, JAPAN; akayama, Yokohama-shi, JAPAN; ahda, Yokohama-shi, JAPAN; ahda **********************************	RULE  Ia, Yokohama-shi, JAPAN; akayama, Yokohama-shi, JAPAN; bita, Fujisawa-shi, JAPAN; bita, Fujisawa-shi, JAPAN; bita, Fujisawa-shi, JAPAN; bitan is a CON of 10/098,478 03/18/2002 PAT 7,061,600 which is PAT 6,404,498 ON of 08/539,886 10/06/1995 PAT 5,774,222  ICATIONS  REIGN FILING LICENSE GRANTED  REIGN FILING LICENSE GRANTED  STATE OR COUNTRY JAPAN 30  SHEETS DRAWING 30  AND STATE OR COUNTRY JAPAN 30  SHEETS DRAWING 30  AND STATE OR COUNTRY JAPAN 30  EES: Authority has been given in Paper or to charge/credit DEPOSIT ACCOUNT or for following:	RULE  Ia, Yokohama-shi, JAPAN; akayama, Yokohama-shi, JAPAN; alida, Yokohama-shi, JAPA	RULE    Ia, Yokohama-shi, JAPAN; akayama, Yokohama-shi, JAPAN; hida, Yokoha